

	Product Change Notification	PCN Nr.: 21007 Date: 05.12.2021 Page: 1 of 1
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PCN Issue date: 05.12.2021

PCN effective date: 04.03.2022

Products affected: INAP375R

Change description:

Change from Au bonding wires to Cu bonding wires.

Reason for change:

Change to mainstream bonding process at final assembly site.
Au bonding share for LQFP package is <5%.

Impact of change:

Higher process stability. No impact on customer application.

Traceability:

With clean date code.

Additional Information:

Delta Qualification Plan according ZVEI Change ID:

- SEM-PA-08 (additional readouts according AEC Q006 due to Cu wire bond)
- Evaluation level: C (Component level)

Originator: Q		Approval: G, S
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